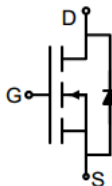
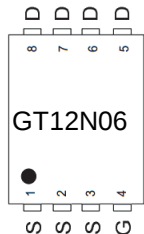


N-Channel Enhancement Mode Power MOSFET

Description The GT12N06S uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications. General Features ● V_{DS} ● I_D (at $V_{GS} = 10V$) ● $R_{DS(ON)}$ (at $V_{GS} = 10V$) ● $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) ● 100% Avalanche Tested ● RoHS Compliant 60V 12A < 9mΩ < 13mΩ Application ● Synchronous Rectification in SMPS or LED Driver ● UPS ● Motor Control ● BMS ● High Frequency Circuit		 Schematic Diagram  Marking and pin assignment  SOP-8	
Device	Package	Marking	Packaging
GT12N06S	SOP-8	GT12N06	4000pcs/Reel

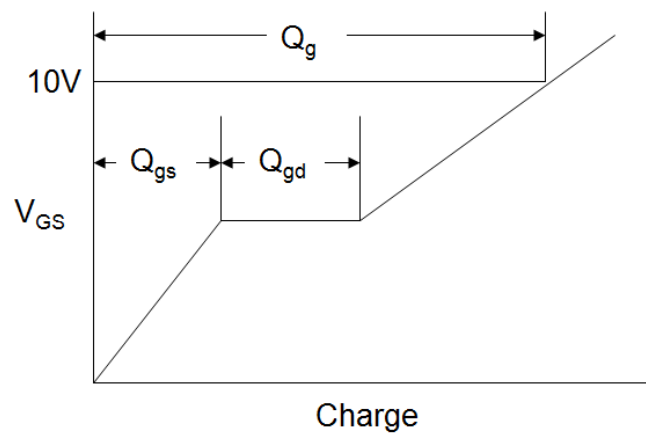
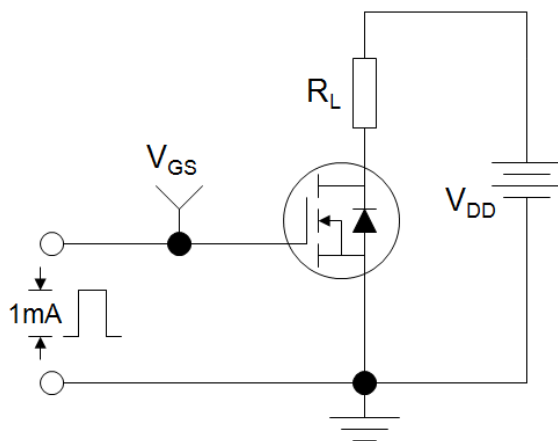
Absolute Maximum Ratings $T_C = 25^\circ C$, unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Continuous Drain Current	I_D	12	A
Pulsed Drain Current (note1)	I_{DM}	48	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	P_D	3.1	W
Single pulse avalanche energy (note3)	E_{AS}	195	mJ
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	$^\circ C$
Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	40	$^\circ C/W$

Specifications T _J = 25°C, unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	60	--	--	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60V, V _{GS} = 0V	--	--	1	μA
Gate-Source Leakage	I _{GSS}	V _{GS} = ±20V	--	--	±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.1	1.7	2.5	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 12A	--	7.6	9.0	mΩ
		V _{GS} = 4.5V, I _D = 12A	--	10.5	13	
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =12A	30	--	--	S
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 30V, f = 1.0MHz	--	1988	--	pF
Output Capacitance	C _{oss}		--	470	--	
Reverse Transfer Capacitance	C _{rss}		--	14	--	
Total Gate Charge	Q _g	V _{DS} = 30V, I _D = 12A, V _{GS} = 10V	--	31	--	nC
Gate-Source Charge	Q _{gs}		--	6	--	
Gate-Drain Charge	Q _{gd}		--	5	--	
Turn-on Delay Time	t _{d(on)}	V _{DD} = 15V, I _D = 12A, R _G = 3Ω	--	10.5	--	ns
Turn-on Rise Time	t _r		--	4.5	--	
Turn-off Delay Time	t _{d(off)}		--	29.5	--	
Turn-off Fall Time	t _f		--	8	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I _S	T _C = 25°C	--	--	12	A
Body Diode Voltage	V _{SD}	T _J = 25°C, I _{SD} = 12A, V _{GS} = 0V	--	--	1.2	V

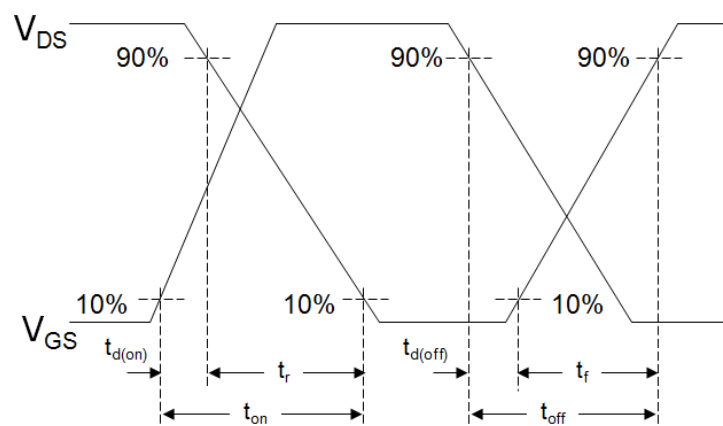
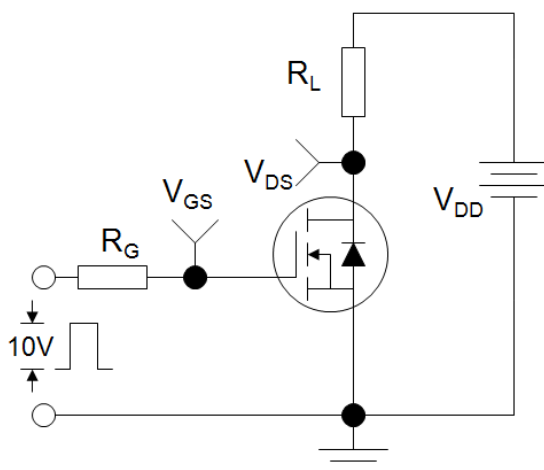
Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical R_G
3. EAS condition : $T_J=25^{\circ}\text{C}$, $V_{DD}=50V, V_{GS}=10V, L=0.5mH, R_g=25\Omega$

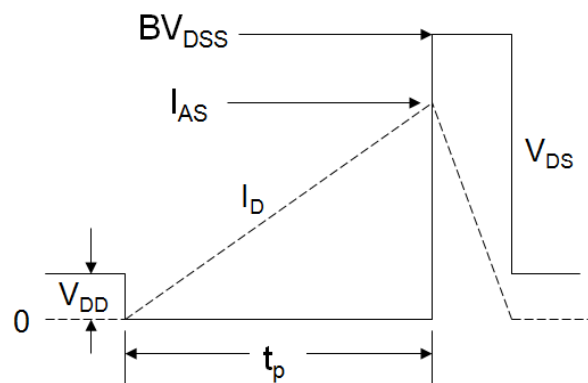
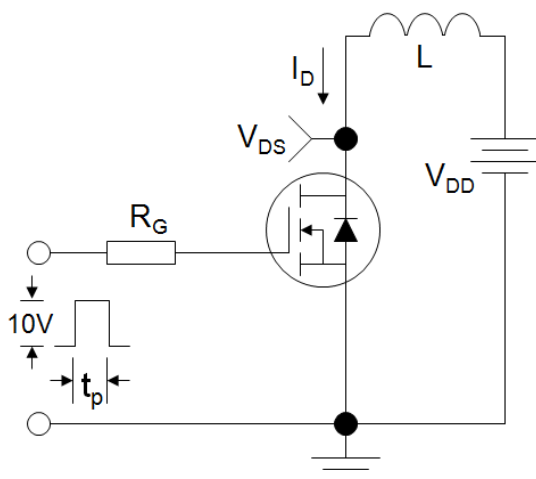
Gate Charge Test Circuit



EAS Test Circuit



Switch Time Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

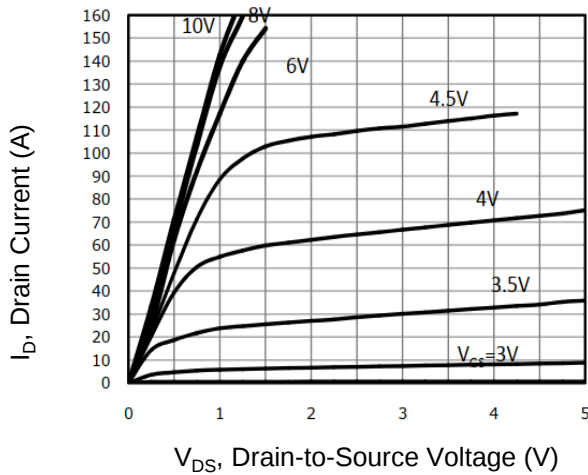


Figure 2. Transfer Characteristics

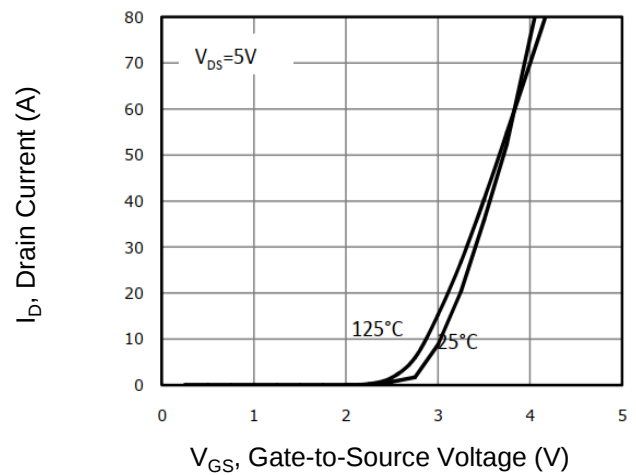


Figure 3. Gate Charge

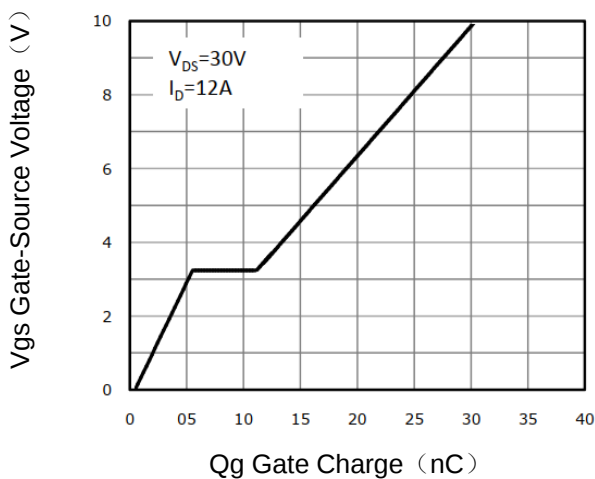


Figure 4. Drain Source On Resistance

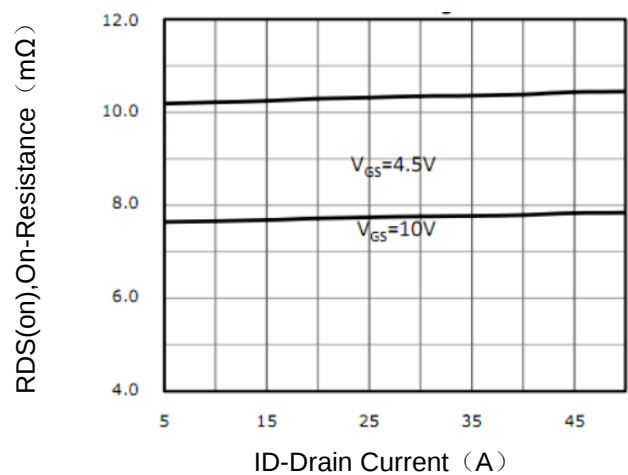


Figure 5. Capacitance vs Vds

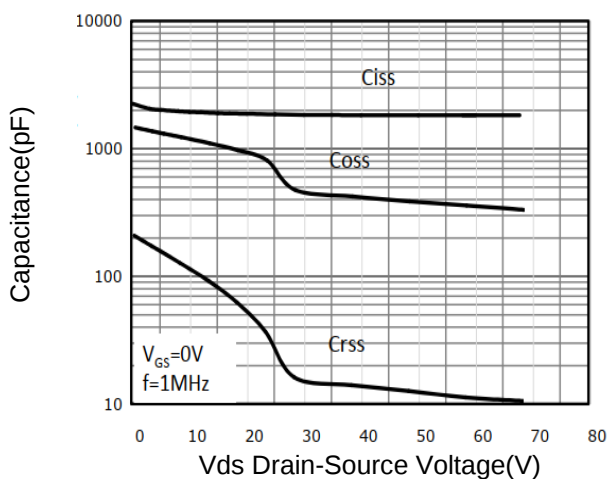
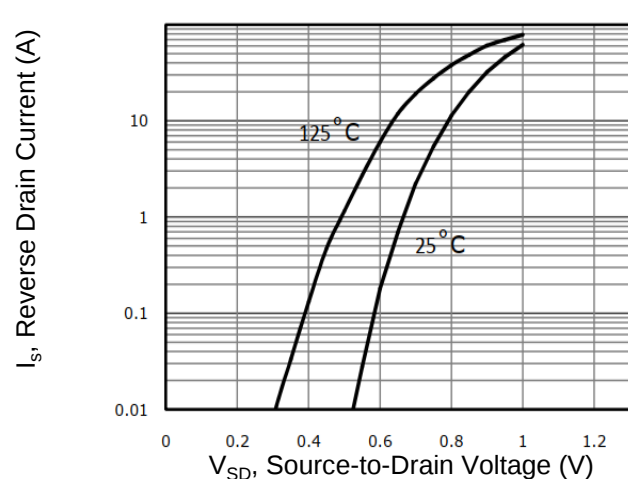


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

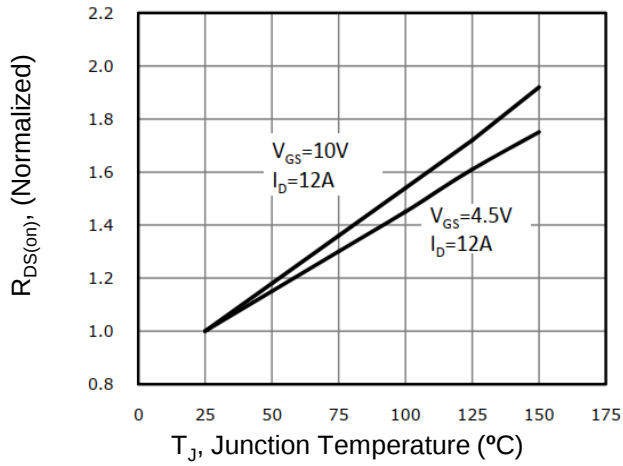


Figure 8. Safe Operation Area

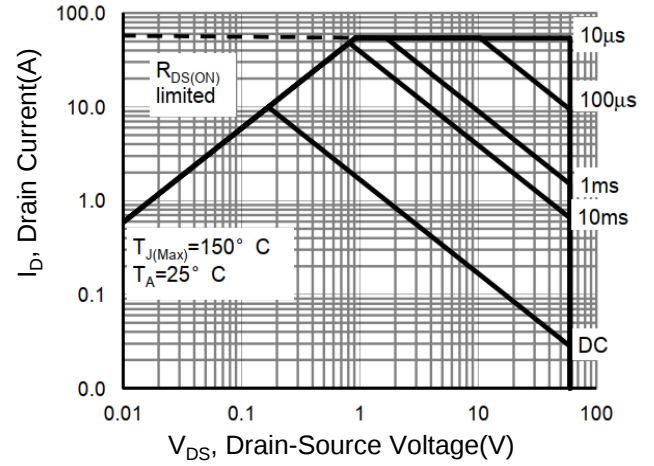
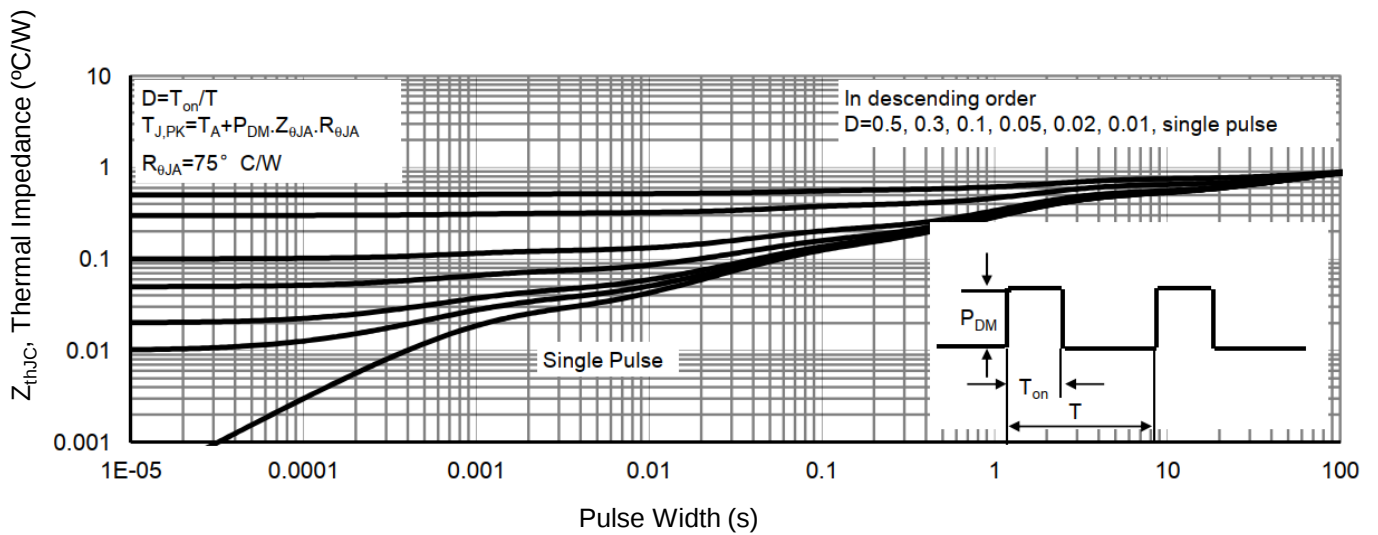
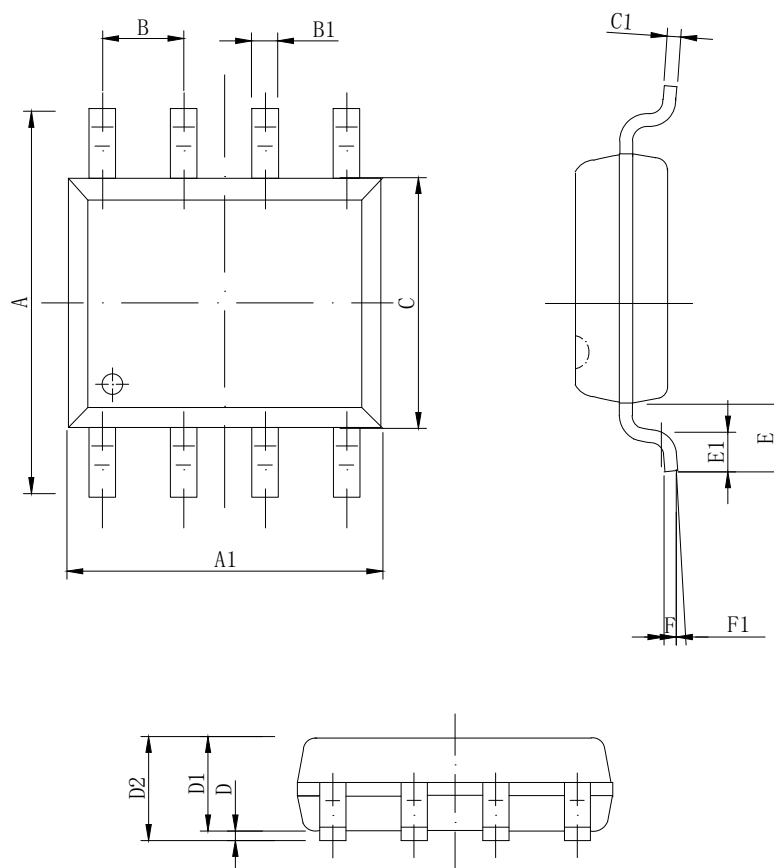


Figure 9. Normalized Maximum Transient Thermal Impedance



SOP-8 Package information



DIM	MIN	NOM	MAX
A	5.800	6.000	6.200
A1	4.800	4.900	5.000
B	1.270BSC		
B1	0.35 ^ 8x	0.40 ^ 8x	0.45 ^ 8x
C	3.780	3.880	3.980
C1	—	0.203	0.253
D	0.050	0.150	0.250
D1	1.350	1.450	1.550
D2	1.500	1.600	1.700
E	1.060 REF		
E1	0.400	0.700	0.100
F	0.250BSC		
F1	2°	4°	6°

All Dimensions in mm